

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yeou-Ching LEE et al

Serial No.: 10/046693



Group Art Unit: 1732

Filed: January 17, 2002

For: MOLDING PROCESS FOR MANUFACTURING
A MOLDED ARTICLE

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Commissioner of Patents
Washington, DC 20231

Sir:

As a means of complying with the duty of disclosure under 37 CFR §1.56, and in accordance with 37 CFR §§1.97 and 1.98, Applicant(s), through the undersigned attorney, submits this Information Disclosure Statement. The patents, publications or other information submitted herewith are listed on the attached Form PTO-1449 and copies are attached.

A complete translation of the foreign language documents is not readily available, however, an English abstract for each is attached.

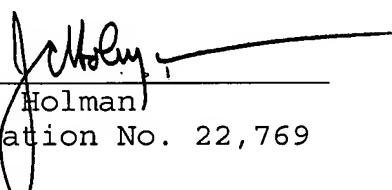
Also attached is a copy of the Form PTO-892 issued in the corresponding CIP application (Serial No. 09/680295 now U.S. Patent 6337044).

In accordance with 37 CFR §1.97(b) (1) or (2), this Information Disclosure Statement is being filed either within three months of the filing date of the above-identified application, or within three months of the date of entry into the national stage of the above-identified application as set forth in 37 CFR §1.491. Accordingly, no fee is required.

Respectfully submitted,

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